Vishay Siliconix

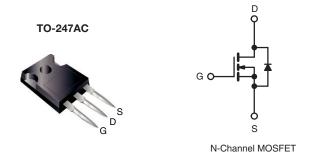
COMPLIANT

HALOGEN

FREE

E Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.099			
Q _g (Max.) (nC)	150			
Q _{gs} (nC)	24			
Q _{gd} (nC)	42			
Configuration	Single			



FEATURES

- Low Figure-of-Merit (FOM): Ron x Qa
- Low Input Capacitance (Ciss)
- · Reducted Switching and Conduction Losses
- Ultra Low Gate Charge (Qa)
- Avalanche Energy Rated (UIS)
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and Telecom Power Supplies
- Switch Mode Power Supplies (SMPS)
- Power Factor Correction Power Supplies (PFC)
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
 - Renewable Energy
 - Solar (PV Inverters)

ORDERING INFORMATION			
Package	TO-247AC		
Lead (Pb)-free	SiHG33N60E-E3		
Lead (Pb)-free and Halogen-free	SiHG33N60E-GE3		

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600		
Gate-Source Voltage				± 20	V	
Gate-Source Voltage AC (f > 1 Hz)			V_{GS}	30		
Continuous Drain Current (T, = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	1	33	А	
Continuous Drain Current (1) = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	I _D	21		
Pulsed Drain Current ^a			I _{DM}	88		
Linear Derating Factor				2.2	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	793	mJ	
Maximum Power Dissipation			P_{D}	278	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	37	V/ns	
Reverse Diode dV/dt ^d			uv/ut	12	V/115	
Soldering Recommendations (Peak Temperature)c for 10 s			300	°C		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7.5 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	=	40	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.45	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		_			l .	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} :	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}		= 600 V, V _{GS} = 0 V /, V _{GS} = 0 V, T _J = 125 °C	-	-	1 10	μΑ
Drain-Source On-State Resistance	D	$V_{DS} = 460 \text{ V}$ $V_{GS} = 10 \text{ V}$		-	0.083	0.099	Ω
Forward Transconductance ^a	R _{DS(on)}		I _D = 16.5 A = 30 V, I _D = 16.5 A		11	0.099	S
Dynamic	9 _{fs}	VDS -	- 30 V, ID = 10.3 A	_			
Input Capacitance	C _{iss}		V _{GS} = 0 V,	_	3508	Ι _	l
Output Capacitance	C _{oss}	+	$V_{GS} = 0 V,$ $V_{DS} = 100 V,$		156		-
Reverse Transfer Capacitance	C _{rss}	+	f = 1 MHz		6	_	
Effective output capacitance, energy related ^b	C _{o(er)}			-	136	-	pF
Effective output capacitance, time related ^c	$C_{o(tr)}$	$V_{GS} = 0$	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V to } 480 \text{ V}$		468	-	
Total Gate Charge	Qg		V _{GS} = 10 V		100	150	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V			24	-	nC
Gate-Drain Charge	Q _{gd}	1		-	42	-	
Turn-On Delay Time	t _{d(on)}		$V_{DD} = 480 \text{ V}, I_{D} = 16.5 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		28	56	ns
Rise Time	t _r	V _{DD} =			60	90	
Turn-Off Delay Time	t _{d(off)}	$R_g = 1$			99	150	
Fall Time	t _f	7		-	54	80	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.7	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	33	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	88	- A
Diode ForwardVoltage	V _{SD}	T _J = 25 °C, I _S = 16.5 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}			-	503	1006	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S,$		-	8.5	17	μC
Reverse Recovery Current	I _{RRM}	dl/dt = 100 A/ μ s, V _R = 20 V		-	26	-	Α

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- c. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

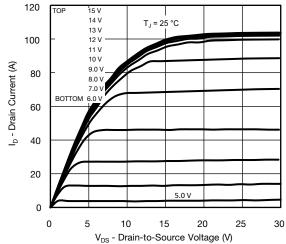


Fig. 1 - Typical Output Characteristics, T_C = 150 °C

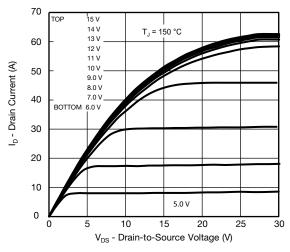


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

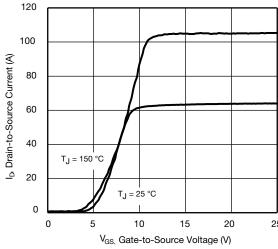


Fig. 3 - Typical Transfer Characteristics

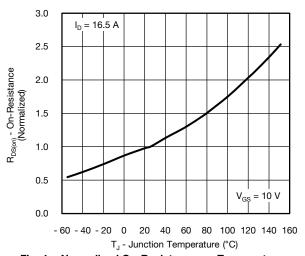


Fig. 4 - Normalized On-Resistance vs. Temperature

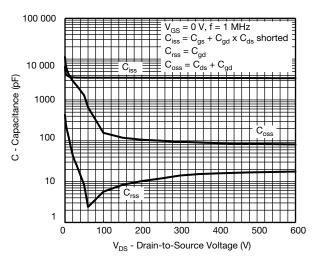


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

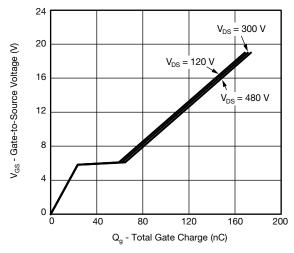


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



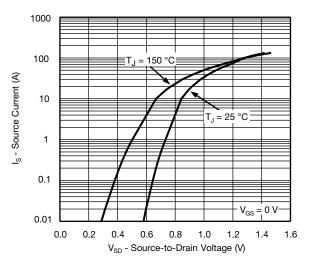


Fig. 7 - Typical Source-Drain Diode Forward Voltage

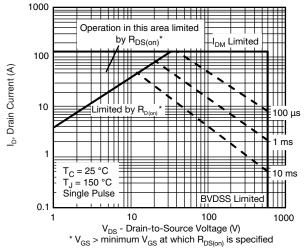


Fig. 8 - Maximum Safe Operating Area

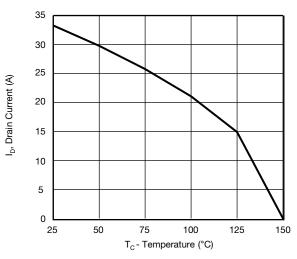


Fig. 9 - Maximum Drain Current vs. Case Temperature

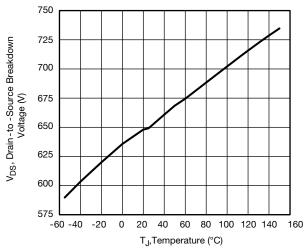


Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature

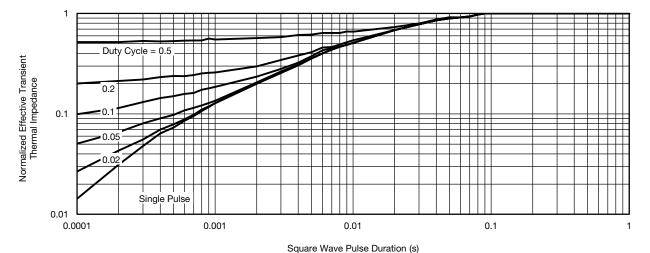


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



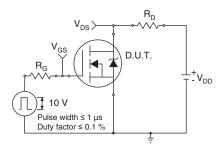


Fig. 12 - Switching Time Test Circuit

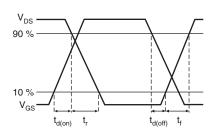


Fig. 13 - Switching Time Waveforms

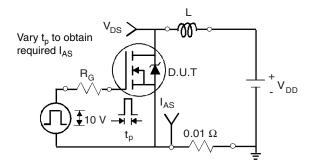


Fig. 14 - Unclamped Inductive Test Circuit

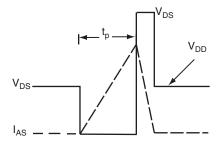


Fig. 15 - Unclamped Inductive Waveforms

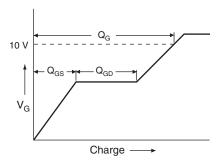


Fig. 16 - Basic Gate Charge Waveform

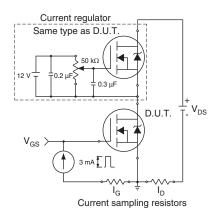
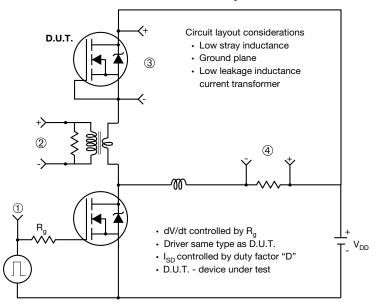


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



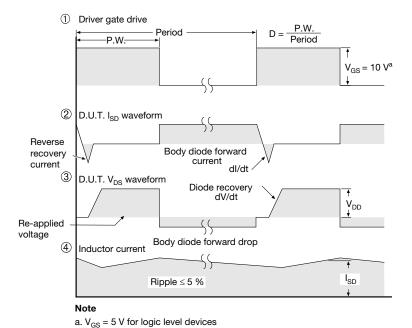
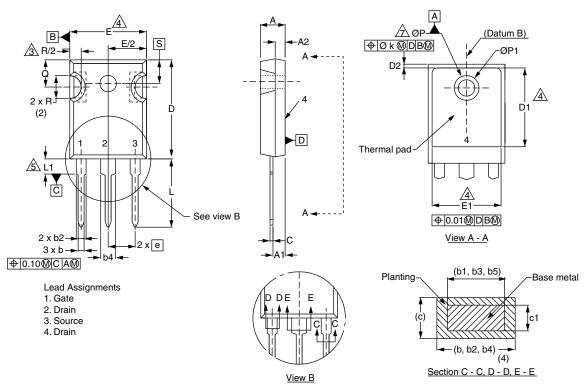


Fig. 18 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91522.



TO-247AC (High Voltage)



	MILLIMETERS		MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.58	5.31	0.180	0.209		
A1	2.21	2.59	0.087	0.102		
A2	1.17	2.49	0.046	0.098		
b	0.99	1.40	0.039	0.055		
b1	0.99	1.35	0.039	0.053		
b2	1.53	2.39	0.060	0.094		
b3	1.65	2.37	0.065	0.093		
b4	2.42	3.43	0.095	0.135		
b5	2.59	3.38	0.102	0.133		
С	0.38	0.86	0.015	0.034		
c1	0.38	0.76	0.015	0.030		
D	19.71	20.82	0.776	0.820		
D1	13.08	-	0.515	-		

	MILLIM	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	
E1	13.72	ı	0.540	ı	
е	5.46	BSC	0.215 BSC		
Øk	0.2	0.254		0.010	
L	14.20	16.25	0.559	0.640	
L1	3.71	4.29	0.146	0.169	
N	7.62	7.62 BSC		0.300 BSC	
ØΡ	3.51	3.66	0.138	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		
0.217 800					

ECN: X13-0103-Rev. D, 01-Jul-13

DWG: 5971

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
 5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.





Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000